

**LTM2882 32LD, BGA, 15mm X 11.25mm X 3.42mm (TABLE OF MATERIAL DECLARATION)**

*The LTM2882 is RoHS compliant per EU RoHS Directive 2003/95/EC.*  
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)				
1	Substrate	Circuit Board	0.1608	Barium Compounds	7727-43-7	0.0029	1.78				
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	105391-33-1, 1156-51-0	0.0350	21.78				
				Copper Metal	7440-50-8	0.0859	53.39				
				Copper Compounds	1328-53-6	0.0000	0.02				
				Ecotoxic substances	7440-38-2, 7440-28-0	0.0000	0.01				
				Gold metal or alloy	7440-57-5	0.0004	0.25				
				Nickel	7440-02-0	0.0026	1.63				
				Zinc	7440-66-6	0.0001	0.06				
				Continuous Filament Fiber Glass	65991-17-3	0.0275	17.12				
				Acrylic Resin	non-disclosure	0.0055	3.39				
				Epoxy Resin	non-disclosure	0.0001	0.04				
				Chromium(III) Oxide	1308-38-9	0.0000	0.00				
				Silica amorphous	7631-86-9	0.0000	0.02				
				Talc;not containing fibers like asbestos	14807-96-9	0.0003	0.21				
				Aromatic Carbonyl compounds	non-disclosure	0.0003	0.19				
				Cyanoguanidine	461-58-5	0.0000	0.01				
				Imidazole system curing reagent	non-disclosure	0.0000	0.00				
				Amine compounds	non-disclosure	0.0000	0.03				
				Leveling agent and others	non-disclosure	0.0001	0.08				
				2	Solder Paste	Alloy	0.0029	Sn	7440-31-5	0.0028	95.00
								Sb	7440-36-0	0.0001	5.00
3	Epoxy		0.0024	Di-ester resin	non-disclosure	0.0002	8.00				
				Functionalized ester	non-disclosure	0.0002	8.00				
4	Passive/Active Components		0.2334	Silver	7440-22-4	0.0020	84.00				
				Fe Oxide	1317-61-9	0.02617	11.21				
				Mn Oxide	1317-35-7	0.00748	3.20				
				Zn Oxide	1314-13-2	0.00374	1.60				
				Glass fibers	65997-17-3	0.01682	7.21				
				Copper (Cu)	7440-50-8	0.05899	25.28				
				Tin (Sn)	7440-31-5	0.01367	5.86				
				Nickel (Ni)	7440-02-0	0.00894	3.83				
				Antimony (Sb)	7440-36-0	0.00210	0.90				
				Adhesive	25068-38-6	0.00280	1.20				
				Resins	25053-15-0	0.02823	12.09				
				Ceramic (Ba Compounds)	12047-27-7	0.06440	27.59				
5	Active Ics	Silicon	0.0045	Silicon	7440-21-3	0.0045	100.00				
6	Wire	Gold	0.0010	Au	7440-57-5	0.0010	99.99				
7	Encapsulation	Epoxy Resin	0.6883	Fused Silica	60676-86-0	0.5314	77.20				
				Epoxy Resin	non-disclosure	0.0613	8.90				
				Phenol Resin	non-disclosure	0.0613	8.90				
				Crytalline Silica	14808-60-7	0.0206	3.00				
				Carbon Black	1333-86-4	0.0034	0.50				
				Metal Hydroxide	non-disclosure	0.0103	1.50				
8	Solder Balls	Alloy	0.0608	Tin	7440-31-5	0.0584	96.50				
				Silver	7440-22-4	0.0021	3.00				
				Copper	7440-50-8	0.0003	0.50				
Total Package Weight			1.1541								

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts